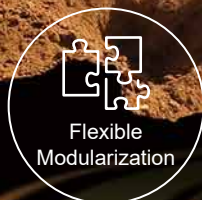


EMBEDDED CORE AI SOLUTION



EMBC-CECT6 intel COM EXPRESS COMPACT SOLUTION FOR MISSION-CRITICAL AI APPLICATIONS

Enabling AI Applications in Harsh Environments

- Wide Temperature -40° ~ 85°C / Wide Voltage 9 ~ 15V
- Shock and Vibration MIL-STD-202H Compliant

Modularized Design for Flexibility

- Quick and Easy CPU & GPU Performance Upgrade
- Customizable I/O Board Functions

High Computing and AI Power in Compact Form Factor

- 13th Generation Intel® Core™ i7 & MXM GPU
- Dual Channel LPDDR5 On-Board Memory 64 GB
- On-Board NVMe 1 TB with M.2 2242 NVMe Expansion

ADVANTECH

SYSTEM STRUCTURE

1 SATA Power Out (5V)

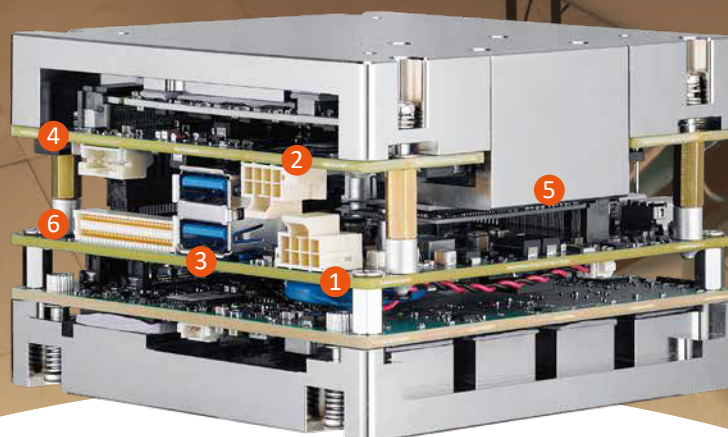
2 SATA Connector for External HD

3 2 x Ethernet

4 5 x MiniDP



- 6
- 4 x USB 2.0
 - 1 x I2C; 1 x SMBus
 - 4 x GP-in; 4 x GP-out
 - 1 x SATA Active LED
 - 1 x M.2 Active LED
 - 2 x Lan Status LEDs
 - 1 x Buzzer; 2 x 2-Wire COM
 - 1 x Power Button-in
 - 1 x Reset Button



1 I/O Board DC-In

2 MXM Carrier Board DC-In

3 2 x USB 3.2 Gen 1

4 MXM Fan Connector

5 M.2 (2242) NVMe Storage

EMBC-CECT6

PERIPHERALS



MXM GPU



Hailo AI Module



NVMe Storage



Thermal Solution



Datasheet



Contact Our Experts